

U.S. National Stage of
PCT/JP2004/004886
PRELIMINARY AMENDMENT

PATENT

IN THE TITLE:

~~LAMINATED~~ BONDED SEMICONDUCTOR SUBSTRATE AND ~~PROCESS FOR PRODUCING~~
~~THE SAME~~ MANUFACTURING METHOD THEREOF

IN THE SPECIFICATION:

Please insert the following paragraph at the beginning of the specification.

This application is a 371 of international application PCT/JP2004/004886, which claims priority based on Japanese patent application No. 2003-099541 filed April 2, 2003, which is incorporated herein by reference.